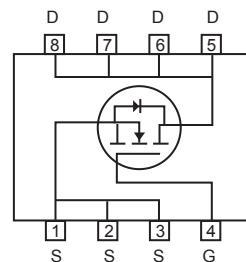
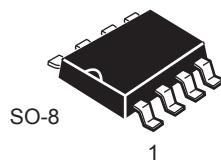


N-Channel Enhancement Mode Field Effect Transistor**FEATURES**

- 60V, 15A, $R_{DS(ON)} = 7.5 \text{ m}\Omega$ @ $V_{GS} = 10\text{V}$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Lead-free plating ; RoHS compliant.
- Surface mount Package.

**ABSOLUTE MAXIMUM RATINGS** $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	15	A
Drain Current-Pulsed ^a	I_{DM}	60	A
Maximum Power Dissipation	P_D	2.5	W
Operating and Store Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient ^b	$R_{\theta JA}$	50	$^\circ\text{C/W}$



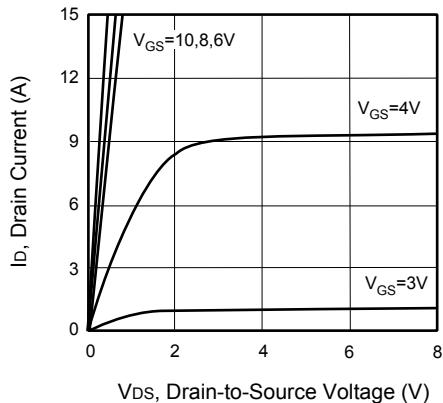
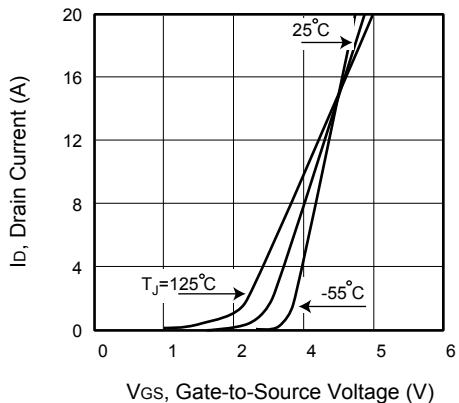
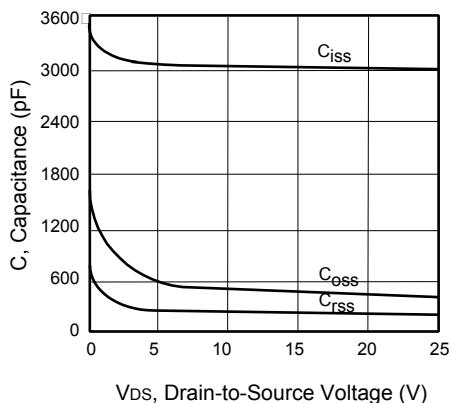
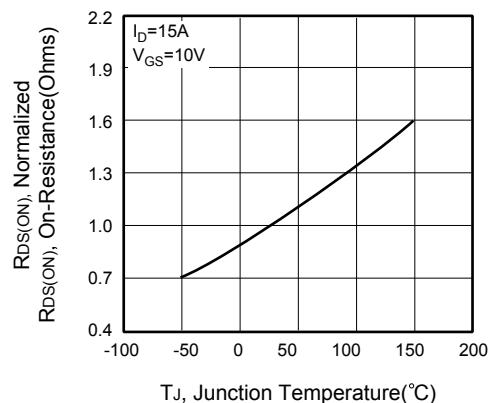
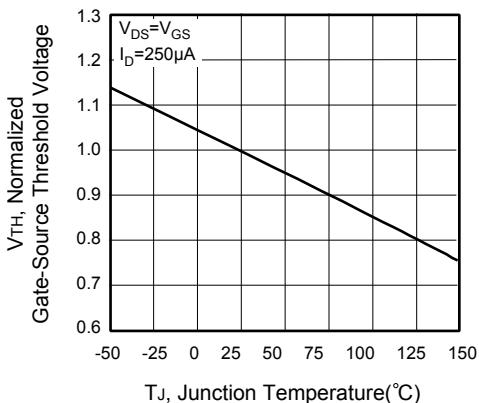
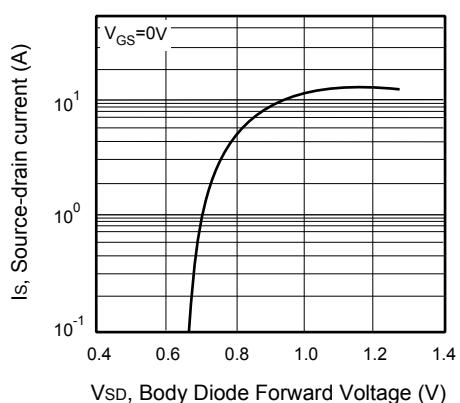
CEM6056

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	60			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 60\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
On Characteristics						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	2		4	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 15\text{A}$		6.2	7.5	$\text{m}\Omega$
Dynamic Characteristics^c						
Forward Transconductance	g_{FS}	$V_{\text{DS}} = 5\text{V}, I_D = 2.6\text{A}$		10		S
Input Capacitance	C_{iss}	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		3205		pF
Output Capacitance	C_{oss}			390		pF
Reverse Transfer Capacitance	C_{rss}			215		pF
Switching Characteristics^c						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 30\text{V}, I_D = 15\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 3.6\Omega$		27	54	ns
Turn-On Rise Time	t_r			14	28	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			60	120	ns
Turn-Off Fall Time	t_f			17	34	ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 48\text{V}, I_D = 15\text{A}, V_{\text{GS}} = 10\text{V}$		75	97.5	nC
Gate-Source Charge	Q_{gs}			12		nC
Gate-Drain Charge	Q_{gd}			28		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current	I_S				2	A
Drain-Source Diode Forward Voltage ^b	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 2\text{A}$			1.2	V

Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
- c.Guaranteed by design, not subject to production testing.

**Figure 1. Output Characteristics****Figure 2. Transfer Characteristics****Figure 3. Capacitance****Figure 4. On-Resistance Variation with Temperature****Figure 5. Gate Threshold Variation with Temperature****Figure 6. Body Diode Forward Voltage Variation with Source Current**

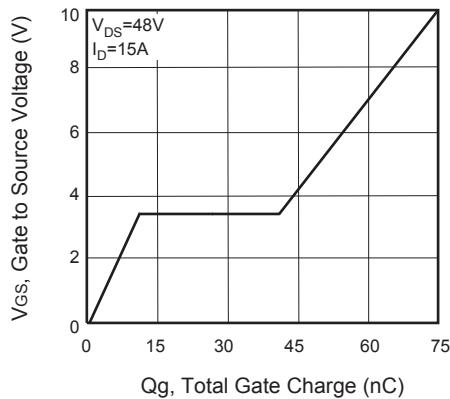


Figure 7. Gate Charge

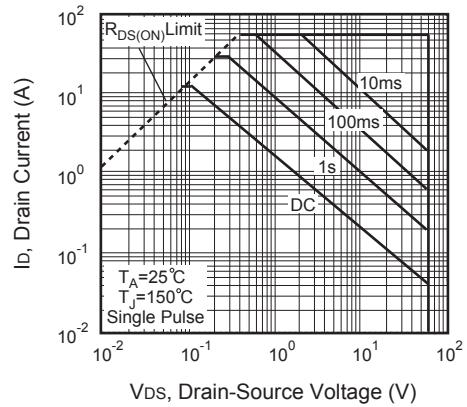


Figure 8. Maximum Safe Operating Area

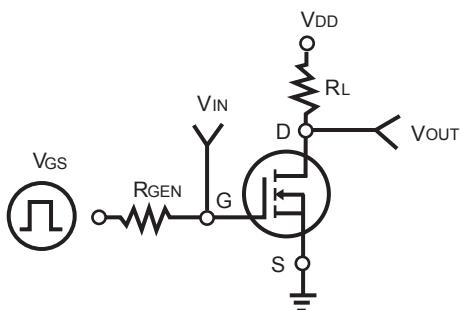


Figure 9. Switching Test Circuit

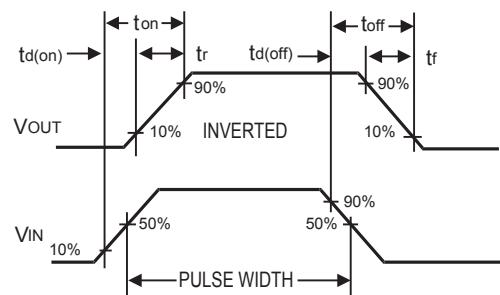


Figure 10. Switching Waveforms

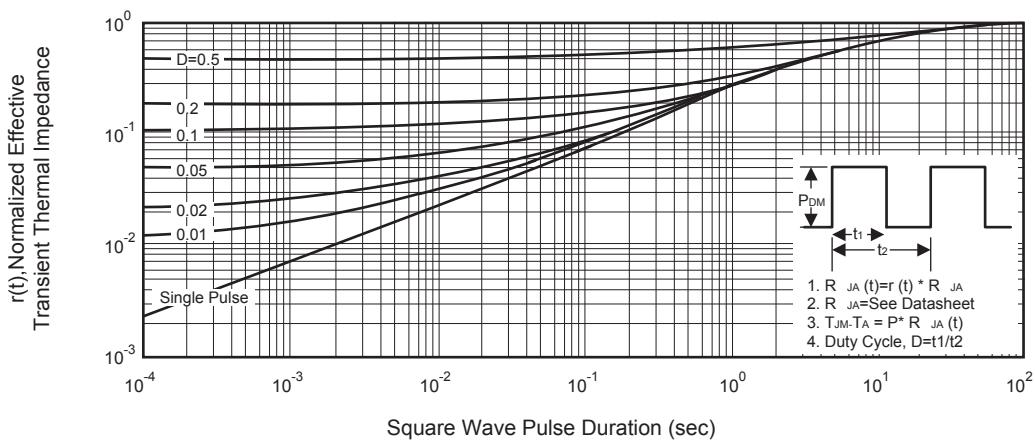


Figure 11. Normalized Thermal Transient Impedance Curve